

**College of Engineering and Technology
DE LA SALLE UNIVERSITY – DASMARIÑAS
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**A STUDY ON THE REDUCTION OF BENT LEAD DEFECTS
THE PROCESS OF FORM AND SINGULATION OF SOIC AT
AMKOR TECHNOLOGY PHILIPPINES INCORPORATED**

**A Practicum Study Presented
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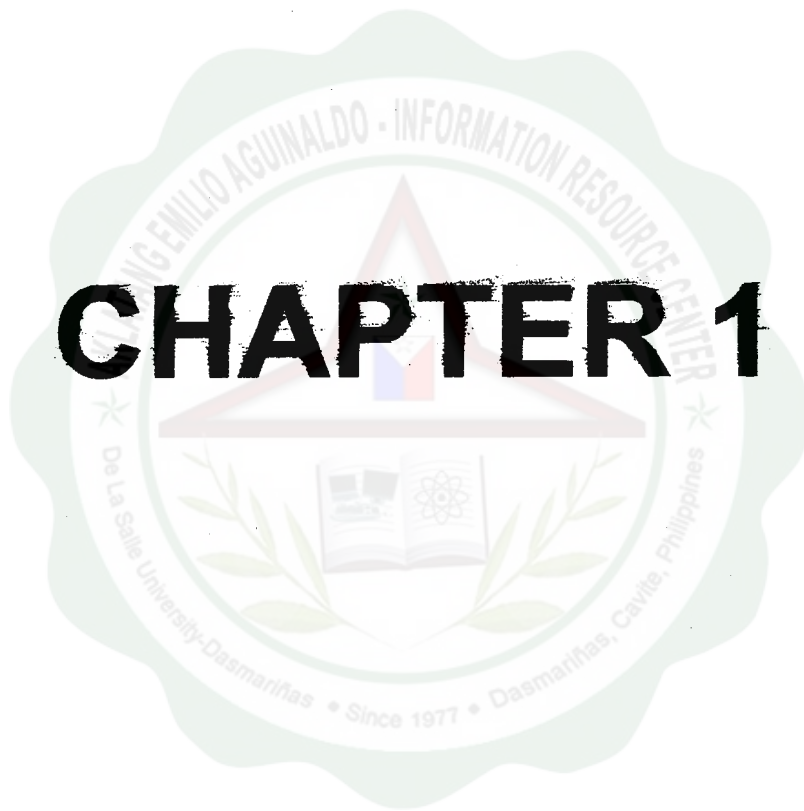
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CHAPTER 1



Background of the Study

The author conducted this study at Amkor Technology Philippines Inc. located at east service road south superhighway, Muntinlupa city. The company is producing different kinds of semiconductors.

The study discusses bent leads defects of SOIC (small outline integrated circuits) of 8 leads. Units that are processed in F/S (form and singulation) machine have recorded bent leads defects. These defects resulted from the manual transferring of units from metal tray to VM see saw to tubes which has been experienced for the past six months. A need to address this issue has now been realized. During the stay of the author in the company, this problem was encountered through on site observation during working hours and through the data gathered.

The SOIC (small outline integrated circuit) has a demand per machine, per shift of 19520 units a day. The company cannot avoid the occurrence of bent lead defects due to manual transferring of units to tubes.

For the past few years, the company was able to maintain good quality products to satisfy the needs of their customers. The main objective of this study is to reduce bent leads defects of SOIC and to find possible solution to the problem.